



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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FBR130

Schottky Rectifier

Features

- 1 Ampere, low forward voltage, less than 500mV
- Compact surface mount package with the same footprint as mini-melf
- Maximum package height of 0.8mm.



SOD-123F
Color Band Denotes Cathode
Mark: 130

Absolute Maximum Ratings * T_a = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{RRM}	Maximum Repetitive Reverse Voltage	30	V
I _{F(AV)}	Average Rectified Forward Current	1	A
I _{FSM}	Non Repetitive Peak Forward Current (Surge applied at rated load conditions half wave, single, phase, 60Hz)	5.5	A
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _{Jmax}	Operating Junction Temperature	-65 to +125	°C

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
R _{θJA}	Thermal Resistance, Junction to Ambient *	73	°C/W
R _{θJL}	Thermal Resistance, Junction to Lead *	23	°C/W

* FR-4 = 3.0 × 5.5 × 0.062" using 1.0 × 0.5" land pads.

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _F	Forward Voltage	@ I _F = 500mA	0.45
		I _F = 1000mA	0.5
I _R	Reverse Current	@V _R = 15V	100
		V _R = 30V	200

Typical Performance Characteristics

Figure 1. Forward Voltage Characteristics

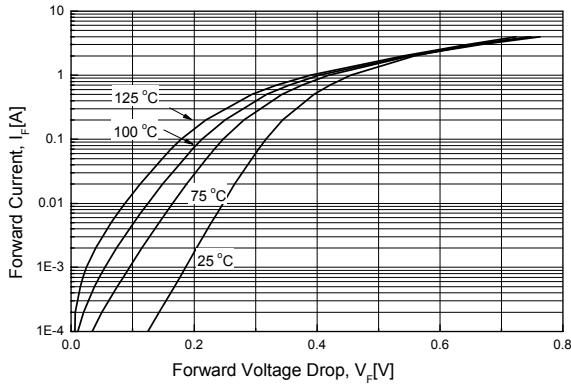


Figure 2. Reverse Current vs Reverse Voltage

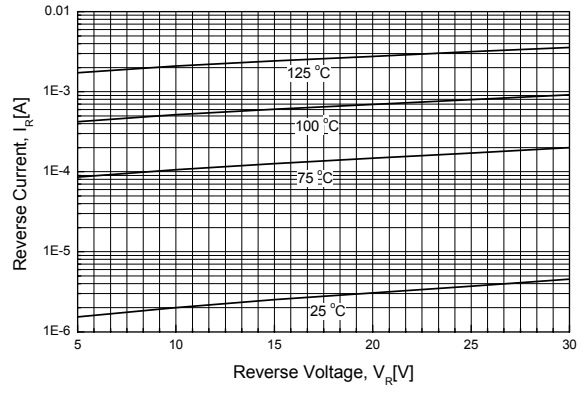
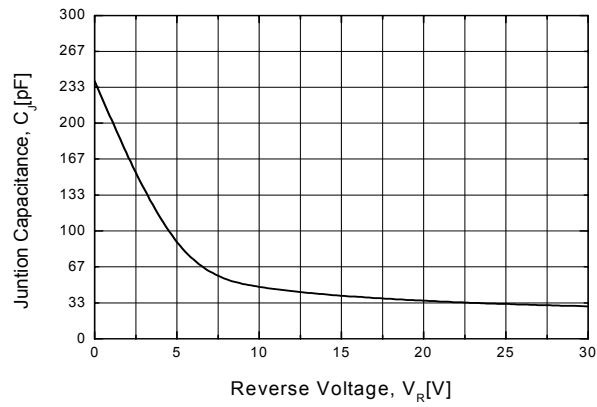
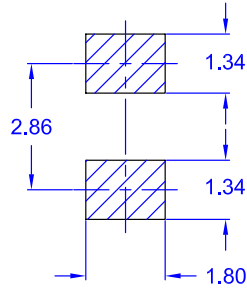
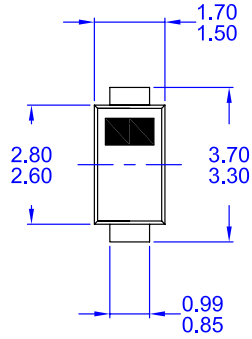


Figure 3. Total Capacitance

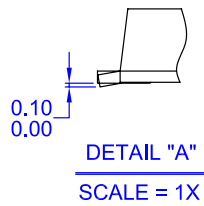
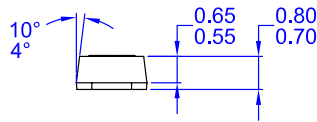
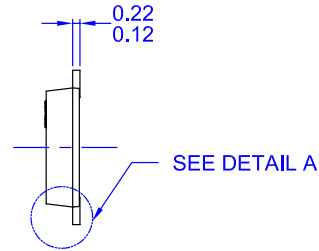
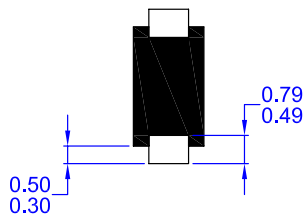


Typical Performance Characteristics

SOD-123F



LAND PATTERN RECOMMENDATION



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 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

Dimensions in Millimeters

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		PowerEdge™	SuperSOT™-6	

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